

isc N-Channel MOSFET Transistor

IRFBC30

FEATURES

- Lower Input Capacitance
- Improved Gate Charge
- Extended Safe Operating Area
- Rugged Gate Oxide Technology

DESCRIPTION

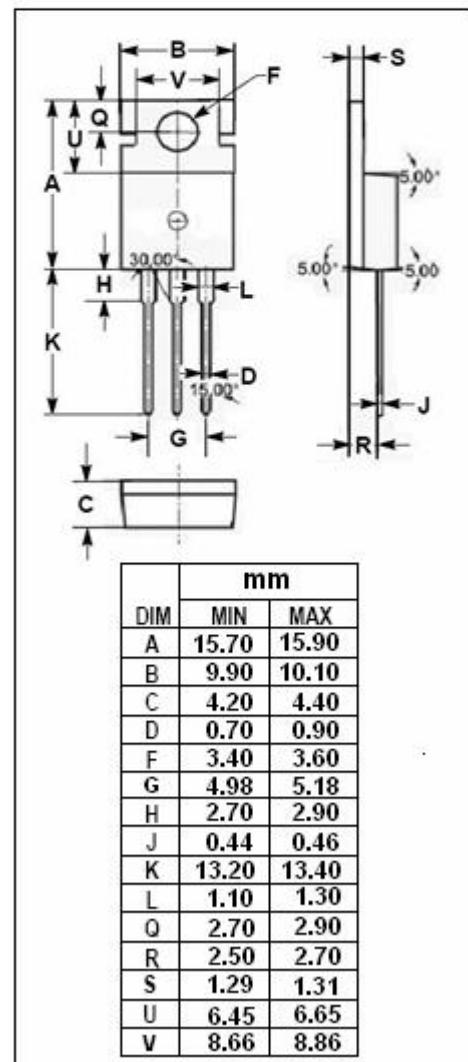
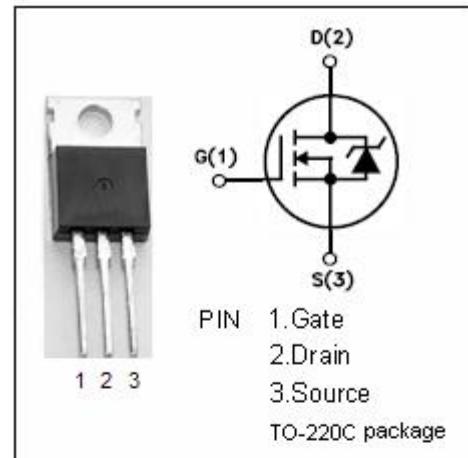
- High current ,high speed switching
- Switch mode power supplies
- DC-AC converters for welding equipment and Uninterruptible power supplies and motor Driver.

ABSOLUTE MAXIMUM RATINGS($T_a=25^\circ\text{C}$)

SYMBOL	PARAMETER	VALUE	UNIT
V_{DSS}	Drain-Source Voltage	600	V
V_{GS}	Gate-Source Voltage-Continuous	± 20	V
I_D	Drain Current-Continuous	3.6	A
I_{DM}	Drain Current-Single Pulse	14	A
P_D	Total Dissipation @ $T_c=25^\circ\text{C}$	75	W
T_J	Max. Operating Junction Temperature	150	$^\circ\text{C}$
T_{stg}	Storage Temperature	-65~150	$^\circ\text{C}$

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	MAX	UNIT
$R_{th j-c}$	Thermal Resistance, Junction to Case	1.7	$^\circ\text{C}/\text{W}$
$R_{th j-a}$	Thermal Resistance, Junction to Ambient	62.5	$^\circ\text{C}/\text{W}$



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ELECTRICAL CHARACTERISTICS

 $T_c=25^\circ\text{C}$ unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN	MAX	UNIT
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0$; $I_D=0.25\text{mA}$	600		V
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$; $I_D=0.25\text{mA}$	2	4	V
$R_{DS(\text{on})}$	Drain-Source On-Resistance	$V_{GS}=10\text{V}$; $I_D=2.2\text{A}$		2.2	Ω
I_{GSS}	Gate-Body Leakage Current	$V_{GS}=\pm 20\text{V}$; $V_{DS}=0$		± 100	nA
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=600\text{V}$; $V_{GS}=0$		1	μA
V_{SD}	Forward On-Voltage	$I_S=3.6\text{A}$; $V_{GS}=0$		1.6	V
C_{iss}	Input Capacitance	$V_{DS}=25\text{V}$, $V_{GS}=0\text{V}$, $F=1.0\text{MHz}$		475	pF
C_{oss}	Output Capacitance			72	pF
C_{rss}	Reverse Transfer Capacitance			10	pF